Ultrabarriers by Atomic Layer Deposition

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## Outline

- 1. Al<sub>2</sub>O<sub>3</sub> ALD barriers on PEN & PET
- 2. Critical tensile strains for  $Al_2O_3 ALD$ films on PEN
  - 3. Flexible alloy barriers using Al<sub>2</sub>O<sub>3</sub> ALD & Alucone MLD
    - 4. H<sub>2</sub>O Corrosion & Al<sub>2</sub>O<sub>3</sub> ALD multilayer barriers

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Atomic Layer Deposition Based on Sequential, Self-Limiting Surface Reactions



# Al<sub>2</sub>O<sub>3</sub> ALD Using TMA & H<sub>2</sub>O



## Conformality of Al<sub>2</sub>O<sub>3</sub> ALD

#### Al<sub>2</sub>O<sub>3</sub> ALD on Trenched Substrate



M. Ritala et al., *Chem. Vap. Deposition* **5**, 7 (1999).

#### Al<sub>2</sub>O<sub>3</sub> ALD on BN Nanoparticles



J.D. Ferguson, S.M.George et al., *Thin Solid Films* **371**, 95 (2000).

# Measurements of Water Vapor Transmission Rate (WVTR)





**Electrical Calcium Test** 



**MOCON** Measurement



Coulometric AQUATRACE Sensor

### WVTRs for Al<sub>2</sub>O<sub>3</sub> ALD on PEN



Optical Ca Test WVTR of  $\leq 5 \times 10^{-5}$ g/m<sup>2</sup>/day at 38°C/85%RH Threshold thickness ~5 nm Equivalent to glass control

P.F. Carcia, S.M. George et al., *J. Appl. Phys.* **106**, 023533 (2009).

### WVTRs for Al<sub>2</sub>O<sub>3</sub> ALD on PET



MOCON Measurement at 38°C/85%RH

Dependence of threshold thickness on Al<sub>2</sub>O<sub>3</sub> ALD growth temperature

→ Postulate more AlOH species in Al<sub>2</sub>O<sub>3</sub> ALD film at lower growth temperatures

P.F. Carcia et al., *Appl. Phys. Lett.* **97**, 221901 (2010).

# Hydrogen Concentration in Al<sub>2</sub>O<sub>3</sub> ALD Films vs. Growth Temperature



Forward Rutherford Scattering Measurements

More AlOH in Al<sub>2</sub>O<sub>3</sub> ALD film at lower growth temperature

 $\rightarrow$  H<sub>2</sub>O may percolate through AlOH regions in Al<sub>2</sub>O<sub>3</sub> ALD film

M.D. Groner, S.M. George et al., *Chem. Mater.* **16**, 639 (2004).

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## Flexible Gas Diffusion Barriers Required for OLEDs & Thin Film Solar



Need Flexible Films for: Bending Thermal Expansion Mismatch



### Cracking vs Tensile Strain on PEN

◀

#### 12.5 nm Film Thickness



### Cracking vs Tensile Strain on PEN

#### 12.5 nm Film Thickness



#### 40 nm Film Thickness



◀





### Crack Density vs. Tensile Strain for Al<sub>2</sub>O<sub>3</sub> ALD Film on PEN



## Critical Tensile Strain for Cracking vs. Al<sub>2</sub>O<sub>3</sub> ALD Film Thickness on PEN



Higher critical tensile strains for cracking for thinner film thicknesses

S.H. Jen, J.A. Bertrand & S.M. George, *J. Appl. Phys.* **109**, 084305 (2011).

### Threshold Bending Radius for Cracking from Threshold Strain

h, Al <sub>2</sub> O <sub>3</sub> Thickness (nm)	ε, Threshold Tensile Strain (%)	R, Threshold Bending Radius (mm)	Strain, $\varepsilon = D/2R$ where D is substrate
5	$2.41 \pm 0.42$	2.59	thickness
10	$1.62\pm0.27$	3.86	
12.5	$1.64 \pm 0.41$	3.81	
15	$1.40 \pm 0.26$	4.46	5 hm Al <sub>2</sub> O <sub>3</sub> ALD
20	$1.19\pm0.22$	5.25	
25	$1.18 \pm 0.24$	5.30	
30	$1.16\pm0.18$	5.39	
40	$0.95\pm0.17$	6.58	
80	$0.52 \pm 0.22$	12.02	

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Molecular Layer Deposition (MLD): Molecular Fragments Deposited During Sequential Surface Reactions



S.M. George et al., Acc. Chem. Res. 42, 498 (2009).

### Alucone MLD Using TMA & EG



### Conformal Alucone MLD Film on BaTiO<sub>3</sub> Nanoparticles



40 Cycles Al<sub>2</sub>O<sub>3</sub> ALD 50 Cycles Alucone MLD ~1.6 Å/Cycle for Alucone MLD at 135°C

A.A. Dameron, S.M. George et al., *Chem. Mater.* **20**, 3315 (2008). Alloy Growth Using Metal Oxide ALD & Metalcone MLD

### **Growth Sequence:**

## M Cycles of Metal Oxide ALD N Cycles of Metalcone MLD

Repeat MNMN...

→ M:N ALD:MLD Alloy

### 1:1 Al<sub>2</sub>O<sub>3</sub> ALD:Alucone MLD Alloy



### Water Vapor Transmission Rate (WVTR) vs Fraction of ALD Cycles



MOCON Measurement

Reach sensitivity limit at ~5:1 ALD:MLD alloy

### Critical Tensile Strain vs Fraction of ALD Cycles for 100 nm Films



Maximum critical tensile strain of ~1.0% for 3:1 ALD:MLD alloy

### Comparison of WVTR and Critical Tensile Strains



ALD:MLD alloys can have higher critical tensile strain & equivalent WVTR compared with  $Al_2O_3 ALD$ 

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### WVTR of Al<sub>2</sub>O<sub>3</sub> & Al<sub>2</sub>O<sub>3</sub>/SiO<sub>2</sub> on Kapton

#### HTO Test, RT/100%RH



 $\rightarrow$  Al<sub>2</sub>O<sub>3</sub> ALD film susceptible to H<sub>2</sub>O corrosion

A.A. Dameron, S.M. George et al., J. Phys. Chem. C 112,4573 (2008).

### Al<sub>2</sub>O<sub>3</sub> ALD Barrier Deposited Directly on Ca Film

#### 18.7 nm $AI_2O_3$ ALD film, 70°C/28%RH







A) 23.6 hr



C) 37.0 hr



B) 30.6 hr



D) 55.0 hr

### Sudden "Blooming" of Circular Spots at Threshold Time



ALD film resulting from  $H_2O$  corrosion.

### Ca Conductance Displays Little Change until Close to "Blooming"



### WVTR vs. Number of Al<sub>2</sub>O<sub>3</sub>/SiO<sub>2</sub> Bilayers on Kapton

HTO Test, RT/100%RH



Each Bilayer: 26 nm  $Al_2O_3$  & ~60 nm  $SiO_2$ 

Additional Al<sub>2</sub>O<sub>3</sub>/SiO<sub>2</sub> bilayer lowers WVTR

Cracking may affect thicker films

A.A. Dameron, S.M. George et al., J. Phys. Chem. C 112,4573 (2008).

### WVTR for Al<sub>2</sub>O<sub>3</sub>/ZrO<sub>2</sub> Nanolaminates

Conductance Ca test, 80°C/80%RH



Each bilayer: 2.1 nm  $Al_2O_3$ ; 3.1 nm  $ZrO_2$ 

Threshold thickness of ~40 nm

Postulate zirconium aluminate phase that improves  $H_2O$  corrosion resistance

J. Meyer et al., Appl. Phys. Lett. **96**, 243308 (2010).

## WVTR for $Al_2O_3/ZrO_2$ Nanolaminate vs. ZrO<sub>2</sub> Fraction

#### MOCON Measurement, 38°C/85%RH



Total film thickness ~10 nm

Al<sub>2</sub>O<sub>3</sub> ALD/ZrO<sub>2</sub> ALD cycle ratios from 5:1 to 1:5

Importance of ZrO<sub>2</sub> volume fraction

WVTR at sensitivity limit for  $f(ZrO_2) < 0.5$ 

P.F. Carcia et al., *J. Vac. Sci. Technol. A* **30**, 041515 (2012).

### Flexible ALD-MLD Inorganic-Organic Multilayer Barriers

Al <sub>2</sub> O <sub>3</sub> ALD	
Polymer MLD	
Al <sub>2</sub> O <sub>3</sub> ALD	
Polymer MLD	
Al <sub>2</sub> O <sub>3</sub> ALD	
Polymer Substrate	

## SEM of Al<sub>2</sub>O<sub>3</sub> ALD/AB Alucone MLD/Al<sub>2</sub>O<sub>3</sub> ALD Trilayer on PEN



D.R. Miller, S.M. George et al., *J. Appl. Phys.* **105**, 093527 (2009)

### Conclusions

1.  $Al_2O_3$  ALD film is excellent gas diffusion barrier. WVTR  $\leq 5 \ge 10^{-5} \text{ g/(m^2 day)}$ . Properties depend on deposition temperature.

2.  $Al_2O_3 ALD$  with thicknesses  $\ge 80$  nm crack at tensile strains  $\le 0.5\%$ . Thinner films can achieve  $\ge 2.0\%$  at  $\le 5$  nm.

- 3.  $Al_2O_3$  ALD/Alucone MLD alloys can obtain higher critical tensile strains than  $Al_2O_3$  ALD with comparable WVTR.
- 4. Nanolaminates obtain lower WVTR values. Explanation may include protection from  $H_2O$  corrosion.

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